



Material Content Data Sheet



Sales Product Name		IDP2303B		Issued		20. July 2018		
MA#		MA001722440						
Package		PG-DSO-16-21		Weight*		174.53 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.103	0.63	0.63	6320	6320
leadframe	inorganic material	phosphorus	7723-14-0	0.023	0.01		130	
	non noble metal	zinc	7440-66-6	0.091	0.05		519	
	non noble metal	iron	7439-89-6	1.813	1.04		10386	
wire	non noble metal	copper	7440-50-8	73.601	42.17	43.27	421700	432735
	noble metal	palladium	7440-05-3	0.001	0.00		6	
	non noble metal	copper	7440-50-8	0.103	0.06	0.06	590	596
encapsulation	organic material	carbon black	1333-86-4	0.285	0.16		1633	
	plastics	epoxy resin	-	9.214	5.28		52790	
	inorganic material	silicondioxide	60676-86-0	85.488	48.98	54.42	489807	544230
leadfinish	non noble metal	tin	7440-31-5	1.562	0.90	0.90	8951	8951
plating	noble metal	silver	7440-22-4	0.641	0.37	0.37	3673	3673
glue	plastics	acrylic resin	-	0.134	0.08		769	
	noble metal	silver	7440-22-4	0.476	0.27	0.35	2726	3495
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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